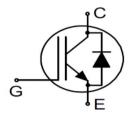


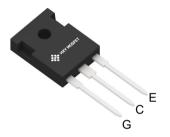
Features

- 650V, 40A IGBT
- Easy paralleling capability due to positive temperature coefficient in V _{CESAT}
- Low EMI
- Low Gate Charge
- Low Saturation Voltage V_{CE(SAT)}
- Maximum junction temperature T_{VJmax}=175°C



Application

- UPS
- EV-Charger
- Solar String Inverter
- Energy Storage Inverter



Key Performance and Package Parameters

Device	V _{CE}	I _C (T _C = 25 °C)	V _{CE(SAT)} (T _{VJ} = 25 °C, V _{GE} = 15 V)	V _F (T _{VJ} = 25 °C, I _F =40A)	Package	Packing
RGS80TS65HRC11	650V	40A	1.6 V	1.8V	TO-247	30PCS

Absolute Maximum Ratings (@ T_{VJ} = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
V _{CE}	Collector emitter voltage		650	V
	(1)	T _C = 25°C	70	А
l _C	DC collector current ⁽¹⁾	T _C = 100°C	40	А
I _{CM}	Pulsed collector current	T _C = 25°C	160	А
	I _F Maximum Diode forward current ⁽¹⁾	T _C = 25°C	70	А
I _F		T _C = 100°C	40	А
I _{FM}	Diode pulsed current	T _C = 25°C	160	А
	Gate-Emitter voltage	T _{VJ} = 25°C	±20	V
V_{GE}	Transient Gate-Emitter Voltage (tp ≤ 10µs, D < 0.010)	T _{VJ} = 25°C	±30	V
Б	D	T _C = 25°C	250	W
P _{tot}	Power Dissipation	T _C = 100°C	125	W
T _{VJ}	Operating Junction Temperature Range		-40 to +175	°C
T _{STG}	Storage Temperature Range		-55 to +150	°C



Thermal Resistance

Symbol	Parameter	Conditions	Max.	Unit
$R_{\theta JA}$	Thermal resistance: junction - ambient		40	°C/W
R _{eJC}	IGBT Thermal resistance: junction - case	IGBT	0.6	°C/W
R _{eJC}	Diode Thermal resistance: junction - case	Diode	0.65	°C/W

Electrical Characteristics (@ T_{VJ} = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Static Cl	naracteristics	,	'		- 1	
V _{(BR)CES}	Collector - Emitter Breakdown Voltage	$V_{GE} = 0V$, $I_C = 0.5mA$	650	-	-	V
		V _{GE} = 15V , I _C = 40A	-	1.6	2.1	V
V _{CESAT}	Collector - Emitter Saturation Voltage	V _{GE} = 15V , I _C = 40A ,T _{VJ} = 125°C	-	1.85	-	V
		V _{GE} = 15V , I _C = 40A ,T _{VJ} = 175°C	-	1.95	-	V
		$V_{GE} = 0V$, $I_C = 40A$	-	1.8	-	V
V _F	Diode forward voltage	$V_{GE} = 0V$, $I_{C} = 40A$, $T_{VJ} = 125^{\circ}C$	-	1.5	-	V
		V _{GE} = 0V , I _C = 40A ,T _{VJ} = 175°C	-	1.35	-	V
V _{GE(th)}	Gate-Emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 250 \mu A$	3.2	4	4.8	V
I _{CES}	Zero Gate voltage Collector current	V _{CE} = 650V , V _{GE} = 0V	-	-	40	μА
I _{GES}	Gate-Emitter leakage current	V _{GE} = ±20V , V _{CE} = 0V	-	-	±100	nA
g _{fs}	Transconductance	V _{GE} =15V, I _C = 40A	-	55	-	S
Dynamic	: Characteristics		•		•	
C _{ies}	Input Capacitance		-	1520	-	pF
C _{oes}	Output Capacitance	$V_{GE} = 0V$, $V_{CE} = 25V$, f = 1MHz	-	110	-	pF
C _{res}	Reverse Transfer Capacitance	1 - 11/11/2	-	11	-	pF
Q_g	Gate Charge		-	57	-	nC
Q_{ge}	Gate to Emitter charge	$V_{GE} = 0 \text{ to } 15V$ $V_{CE} = 520V, I_{C} = 40A$	-	6.5	-	nC
Q_{gc}	Gate to Collector charge	VGE 323 V, 10 137 V	-	17.5	-	nC
Switchir	g Characteristics				,	
t _{d(on)}	Turn-On DelayTime		-	26	-	ns
t _r	Turn-On Rise Time		-	28	-	ns
t _{d(off)}	Turn-Off DelayTime		-	136	-	ns
t _f	Turn-Off Fall Time	$V_{GE} = 15V, V_{CC} = 400V$ $I_{C} = 40A, R_{G(on)} = 15\Omega, RG_{(off)} = 15\Omega$	-	34	-	ns
E _{on}	Turn-on energy	1C 4071, 11G(on) 1012,11G(off) 1012	-	0.9	-	mJ
E _{off}	Turn-off energy		-	0.43	-	mJ
E _{ts}	Total switching energy		-	1.33	-	mJ
Diode R	ecovery Characteristics					
T _{rr}	Reverse recovery time		-	56	-	ns
Q _{rr}	Reverse recovery charge	$V_R = 400 \text{ V}, I_F = 40 \text{ A},$ di/dt = 400 A/µS	-	0.27	-	μС
I _{rrm}	Peak reverse recovery current	α,,αι – του / νμο	-	8.0	-	Α

Notes:

1. The max Collector current rating is package limited



Typical Performance Characteristics

Fig.1 Typical Output characteristics (25°C)

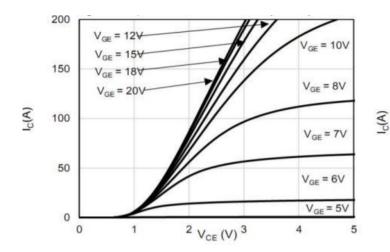


Fig.3 Forward Bias Safe Operating Area

Fig.2 Typical Output characteristics (150°C)

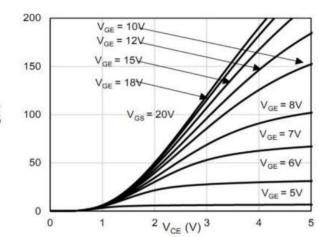


Fig.4 Transfer characteristics

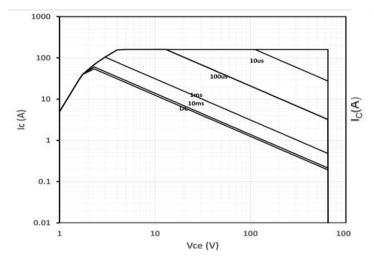


Fig.5 Gate charge characteristics

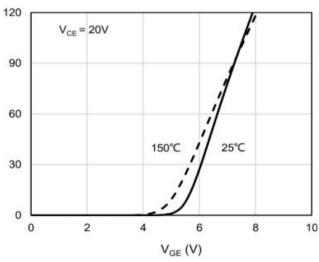
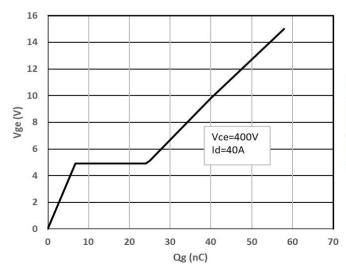
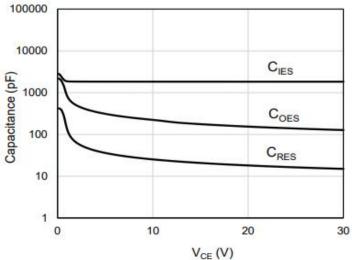


Fig.6 Typical capacitance characteristics







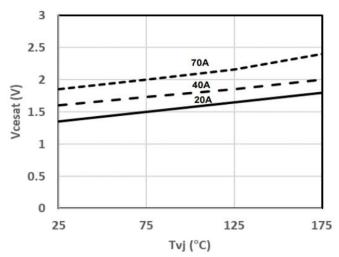


Fig.8 Typical diode VF vs. IF Characteristics

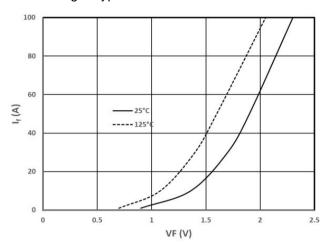


Fig.9 Threshold voltage vs. Junction temperature

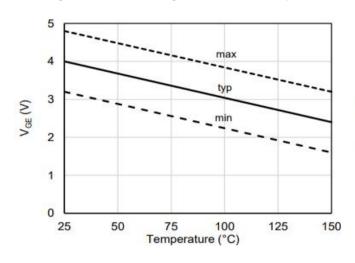


Fig.10 Transient Thermal Impedance IGBT

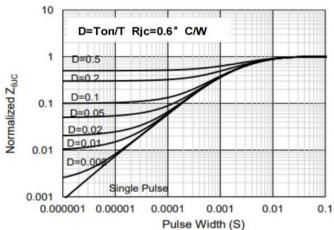
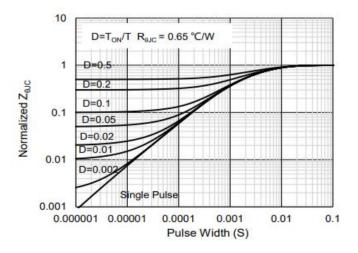
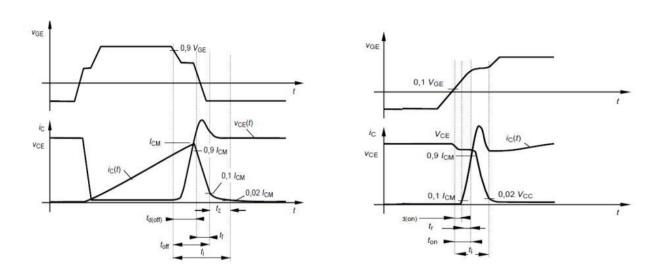


Fig.11 Transient Thermal Impedance Diode

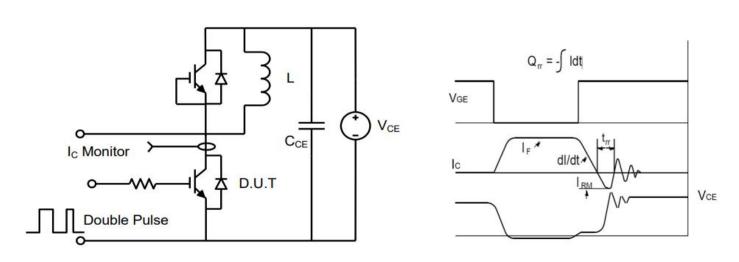


Test Circuit

Switching Test Circuit & Waveforms

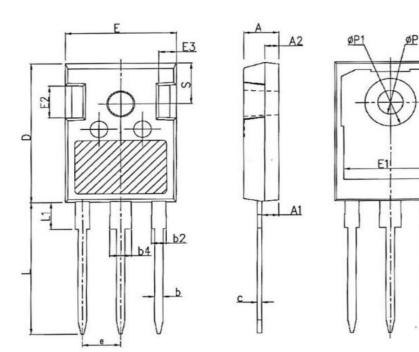


Diode Recovery Test Circuit & Waveforms





Package Mechanical Data(TO-247)



CAMBOI	mm			
SYMBOL	MIN	MOM	MAX	
A	4.80	5.00	5. 20	
A1	2. 21	2.41	2. 59	
A2	1.85	2.00	2. 15	
b	1.11	1.21	1. 36	
b2	1.91	2.01	2. 21	
b4	2.91	3.01	3. 21	
С	0.51	0.61	0.75	
D	20.70	21.00	21.30	
D1	16. 25	16.55	16.85	
E	15. 50	15.80	16. 10	
E1	13.00	13.30	13.60	
E2	4.80	5.00	5. 20	
E3	2.30	2.50	2.70	
е	5. 44BSC			
L	19. 62	19.92	20. 22	
L1_	-	-	4.30	
ФР	3.40	3.60	3.80	
ФР1	-	-	7.30	
S	6. 15BSC			



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